

1

Panasonic's advanced packaging technologies for thin substrates

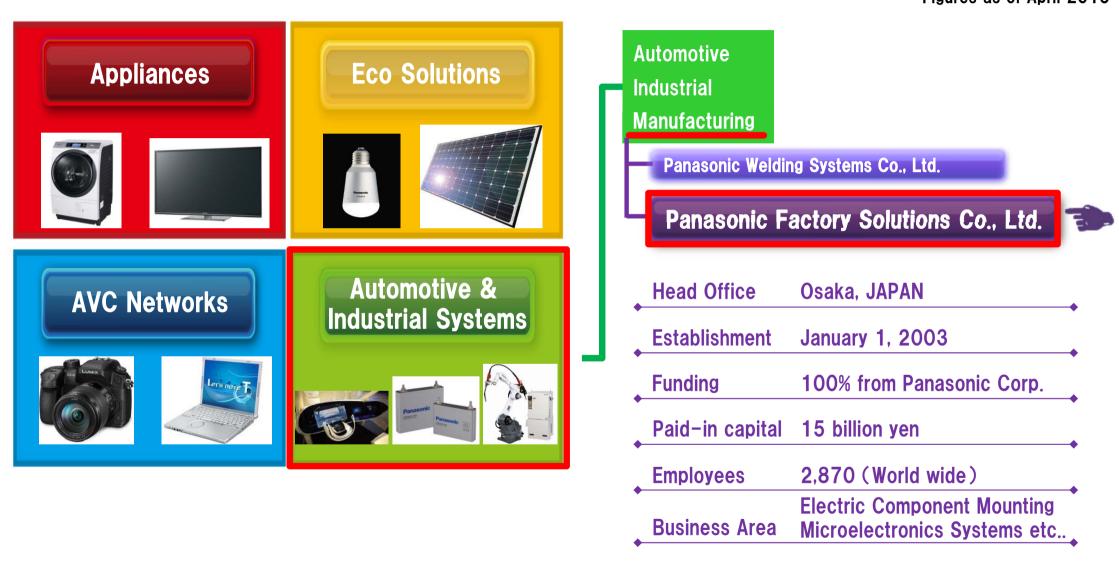
May 27th, 2014

Mitsuru Hiroshima Micro Electronics Division Panasonic Factory Solutions Co., Ltd.

Panasonic's 4 Business Groups and Our Company

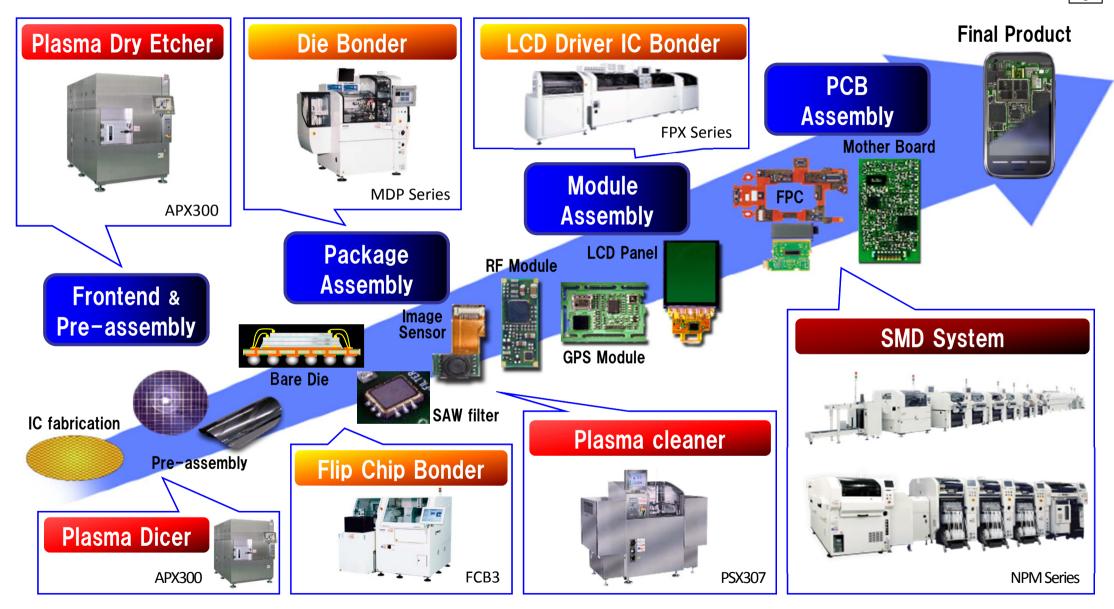
Panasonic

Figures as of April 2013



Panasonic

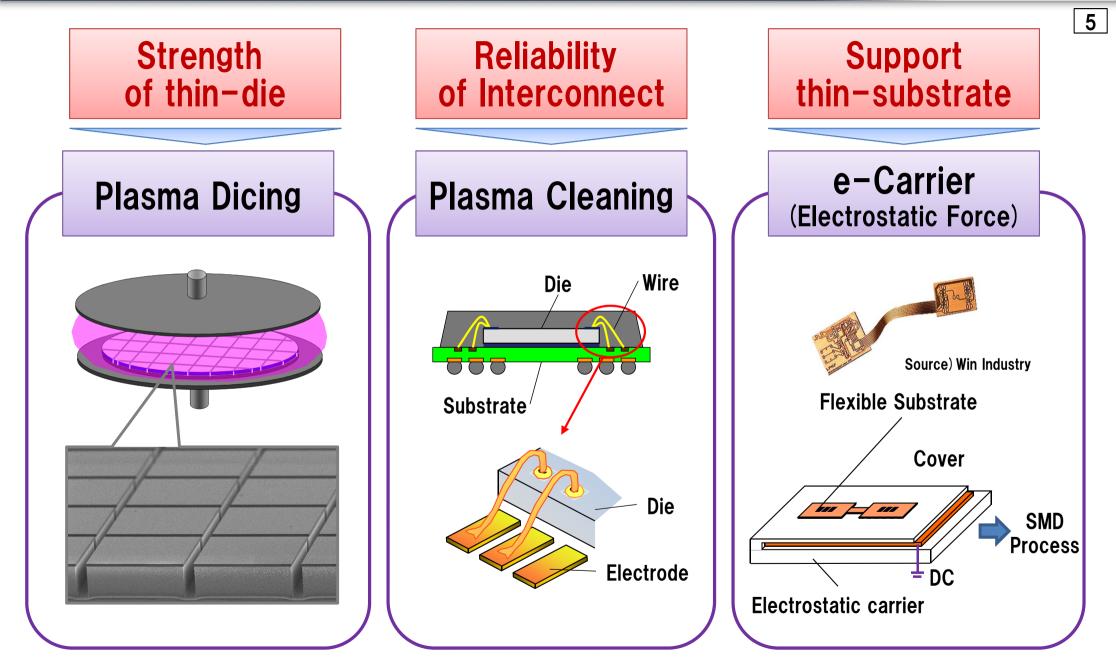
3



Requirements for thin-substrate Manufacturing

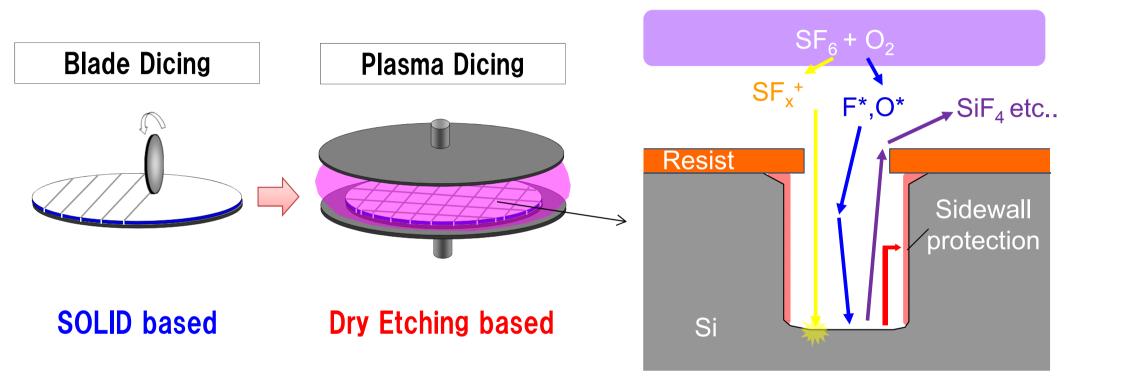


Panasonic's PKG Solutions for thin substrate



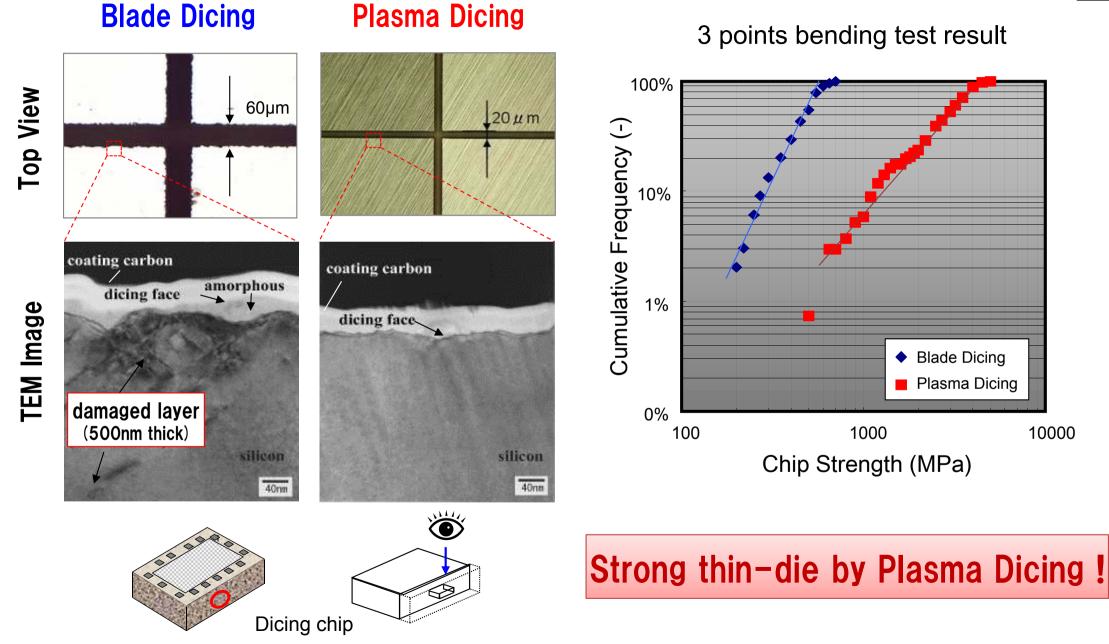


6



Plasma Dicing – Die Strength –

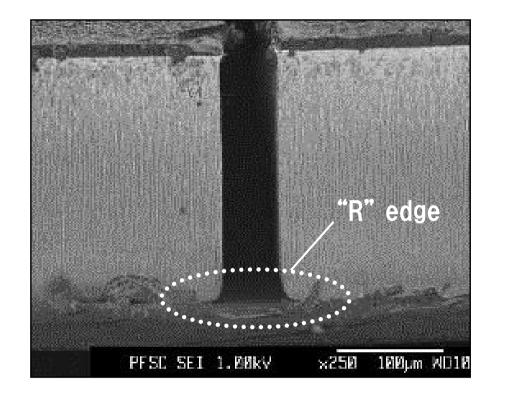


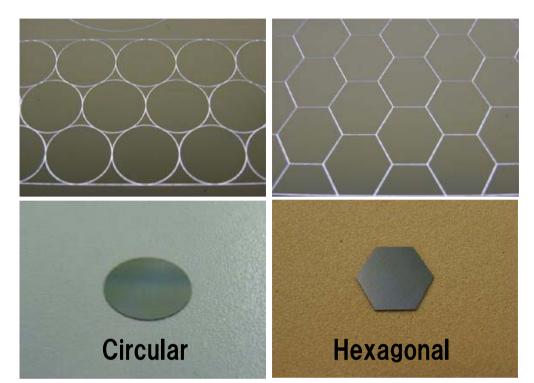


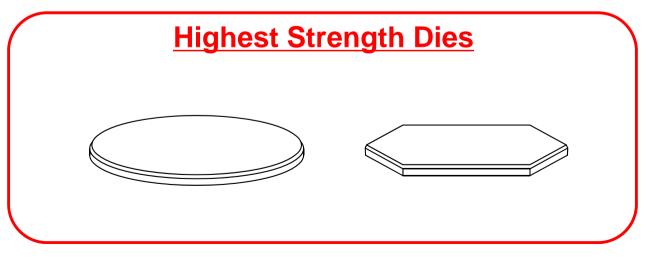
Plasma Dicing – Makes dies stronger –

Panasonic

8

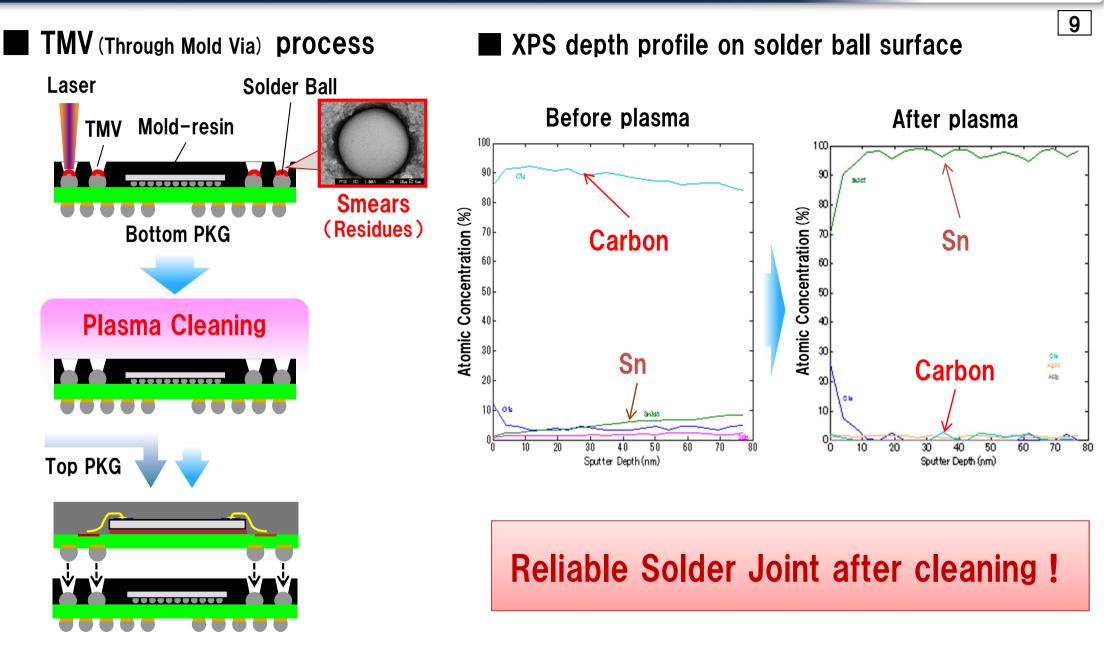






Plasma Cleaning – PoP interconnection –

Panasonic



XPS : X-ray Photoelectron Spectroscopy

Contribute to your thin-sub. manufacturing !



10

Plasma Dicing



APX300

Plasma Cleaning

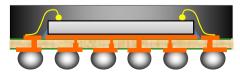
Chip Bonding



MD-P200US

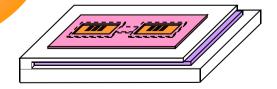
Handling





Panasonic's **PKG techniques**





e-carrier